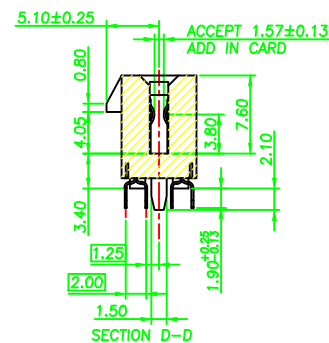
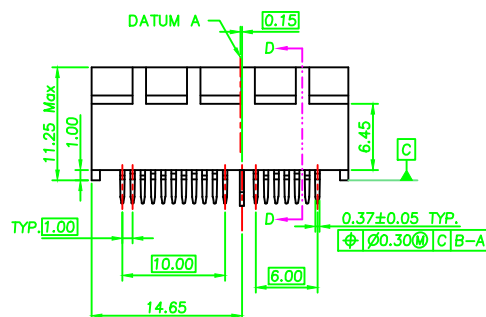
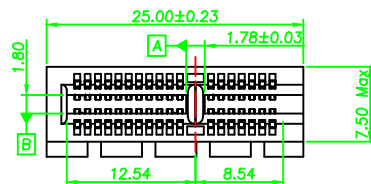
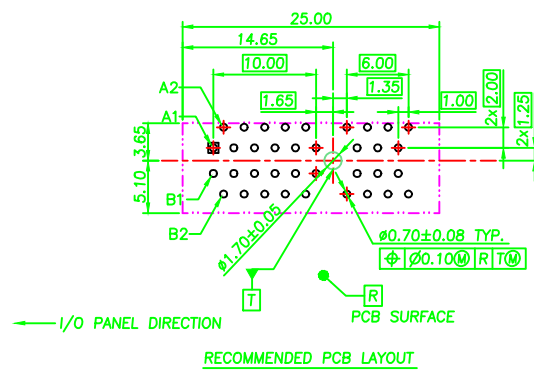
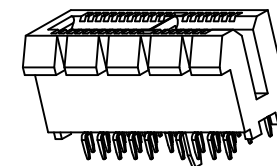


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
04	--	Modification of Layout dimension	2021.10.27	Dorian
05	--	Modify HOOK height	2021.12.07	Dorian



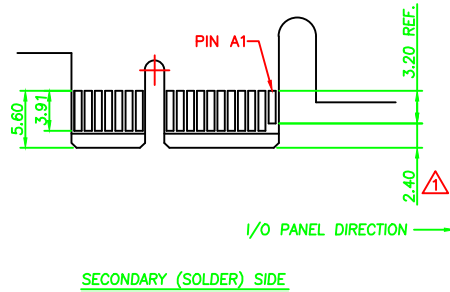
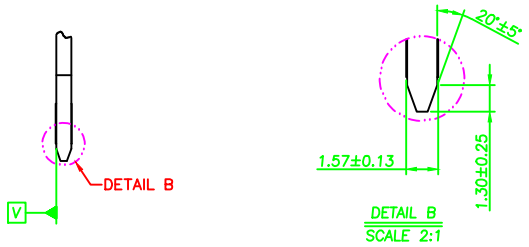
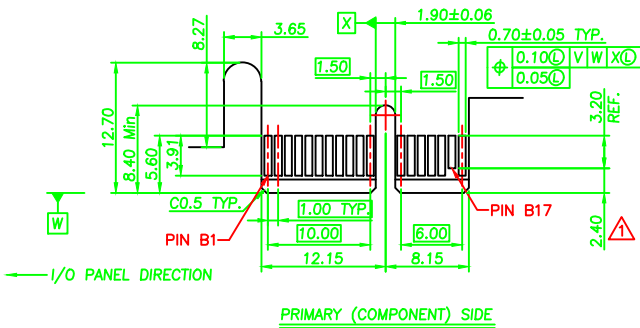
PART P/N:
121P-C1EB-M8 * C

CONTACT AREA GOLD PLATING:
G= GOLD FLASH
B= 15u" GOLD
C= 30u" GOLD



2	CONTACT	COPPER ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" MATTE TIN PLATING OVER NICKEL AT TAIL. GOLD PLATING ON CONTACT AREA.	
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED BLACK	
ITEM	DESCRIPTION	MATERIAL	TREATMENT	
DIM	TOL	DIM	DEG	JOINSOO建舜電子
X	±0.50	X"	±8°	
X.X	±0.35	X.X"	±5°	
X.XX	±0.25	X.XX"	±3°	
X.XXX	±0.15	X.XXX"	±2°	
DESIGN:	DORIAN	2021.12.07	FILE:	DRAW NAME:
CHECK:	DAMON	2021.12.07	DRAW NO.	PCIE-X1 Gen3 36P DIP TYPE CONN
APPROVED	HENRY	2021.12.07	P/N: 121P-C1EB-M8*C	MODEL:
		UNIT: mm	SCALE: 1:1	-
		REV: 05	SHEET: 1/2	

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
04	--	Modification of Layout dimension	2021.10.27	Dorian
05	--	Modify HOOK height	2021.12.07	Dorian



NOTES:
1. NO TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND B17.
2. CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

ADD-IN CARD EDGE-FINGER DIMENSIONS

DIM	TOL	DIM	DEG	JOINSOO建舜電子				
X	±0.50	X°	±8°	FILE:		DRAW NAME: PCIE-X1 Gen3 36P DIP TYPE CONN		
X.X	±0.35	X.X°	±5°					
X.XX	±0.25	X.XX°	±3°					
X.XXX	±0.15	X.XXX°	±2°					
DESIGN:	DORIAN	2021.12.07	DRAW NO.					
CHECK:	DAMON	2021.12.07	P/N: 121P-C1EB-M8*C					
APPROVED	HENRY	2021.12.07	UNIT: mm	SCALE: 1:1	MODEL:	-		
			REV: 05	SHEET: 2/2				

C-DWG